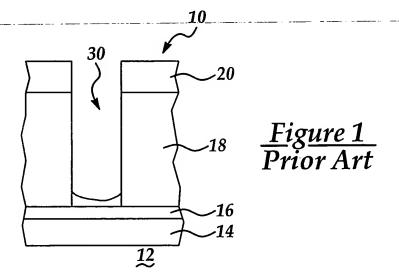
Inventor(s): CHING-TIEN MA ET AL Serial No.: To Be Assigned

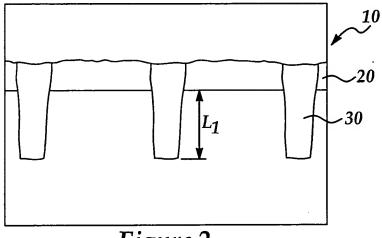
Filed: Herewith

For: METHOD FOR FORMING VIA AND CONTACT HOLES WITH DEEP UV PHOTORESIST

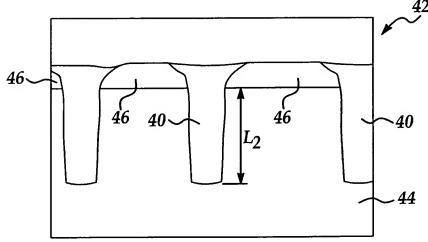
Attorney Docket No.: 67,200-549



1/1



<u>Figure 2</u> Prior Art



<u>Figure 3</u>

中的情况的情况的一种一种一种中央中